



# Material Composition Declaration

## EPC2216

Company Name	Efficient Power Conversion (EPC)	Issue Date:	9/9/2019
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	1.8 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	1.6035	87.2562	89.2789	872562
	Silicon oxide	7631-86-9	0.0063	0.3454		3454
	Silicon nitride	12033-89-5	0.0021	0.1143		1143
	Gallium nitride	25617-97-4	0.0076	0.4155		4155
	Aluminum	7429-90-5	0.0066	0.3580		3580
	Aluminum nitride	24304-00-5	0.0018	0.0992		992
	Titanium	7440-32-6	0.0002	0.0136		136
	Titanium nitride	25583-20-4	0.0009	0.0508		508
	Copper	7440-50-8	0.0002	0.0118		118
	Tungsten	7440-33-7	0.0005	0.0287		287
	Polyimide		0.0108	0.5854		5854
Under Bump Metal	Titanium	7440-32-6	0.0001	0.0065	0.5512	65
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.0100	0.5447		5447
Solder Bump	Tin	7440-31-5	0.1785	9.7122	10.1699	97122
	Silver	7440-22-4	0.0075	0.4068		4068
	Copper	7440-50-8	0.0009	0.0508		508
Sum in total:			1.8377	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.